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(54) Polybutadiene and polyisopropene based thermosetting compositions and method of manufacture thereof

(57) An electrical circuit material is presented which comprises:

(a) a thermosetting composition comprising a polybutadiene or polyisoprene resin and an unsaturated butadiene or isoprene containing polymer capable of participating in crosslinking with said polybutadiene or polyisoprene resin in an amount of from 25 to 50 volume percent;

(b) a woven fabric in an amount from 10 to 40 volume percent;

(c) a particulate filler in an amount of from 5 to 60 volume percent; and

(d) a free radical cure initiator.

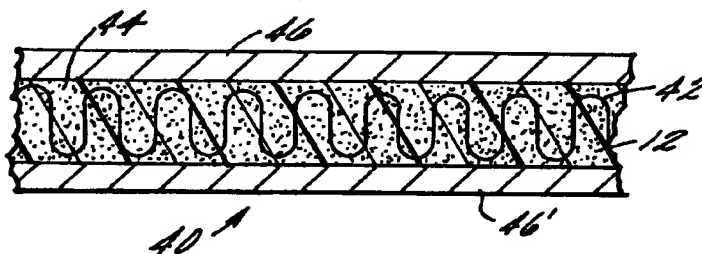


FIG. 2

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Description

This invention relates generally to polybutadiene and polyisoprene based thermosetting compositions and method of manufacture thereof. More particularly, this invention relates to an electrical circuit laminate comprising a thermosetting resin of polybutadiene or polyisoprene.

U.S. Patent 5,223,568 describes a thermosetting composition which is particularly useful for making electrical substrate materials. In general, U.S. Patent, 5,223,568 describes a composition formed from the steps of:

- (a) providing a moldable thermosetting composition that includes 1) polybutadiene or polyisoprene resin which is a liquid at room temperature and which has a molecular weight less than 5,000 and 2) a solid butadiene or isoprene-containing polymer capable of cross-linking with the polybutadiene or polyisoprene resin;
- (b) forming the composition into a shape; and
- (c) curing the composition to produce the electrical substrate material including subjecting the composition to a high temperature cure condition at a temperature greater than about 250°C and less than the decomposition temperature of the composition. This composition thus comprises a two component system, the first component being the polybutadiene or polyisoprene resin and the second component being the solid butadiene or isoprene-containing polymer; all of which are subjected to the high temperature curing cycle (e.g., greater than 250°C).

In preferred embodiments, the solid polymer is a thermoplastic elastomer block copolymer.

U.S. Patent 5,223,568 also describes a composition with a dielectric filler (i.e., a material having a dielectric constant greater than about 1.2 at microwave frequencies) homogeneously dispersed throughout the composition to the extent that when the composition is cured the properties of the cured article, e.g., dielectric constant and coefficient of thermal expansion, do not vary more than about 5% throughout the article.

In preferred embodiments, the composition of U.S. Patent 5,223,568 further includes a crosslinking agent capable of co-curing (i.e., forming covalent bonds) with the polybutadiene or polyisoprene resin thermoplastic elastomer, or both. Examples of preferred crosslinking agents include triallylcyanurate, diallylphthalate, divinyl benzene, a multifunctional acrylate, or combinations of these agents.

When the electrical substrate material includes a dielectric filler, the volume % of the filler (based upon the combined volume of resin, thermoplastic elastomer, crosslinking agent (if any) and filler) is between 5 and 80%, inclusive. Examples of preferred fillers include titanium dioxide (rutile and anatase), barium titanate, strontium titanate, silica (particles and hollow spheres); corundum, wollastonite, polytetrafluoroethylene, aramide fibers (e.g., Kevlar), fiberglass, $\text{Ba}_2\text{Ti}_9\text{O}_{20}$, glass spheres, quartz, boron nitride, aluminum nitride, silicon carbide, beryllia, or magnesia. They may be used alone or in combination.

The method disclosed in U.S. Patent 5,223,568 provides a wide variety of shaped articles having favorable isotropic thermal and dielectric properties. These properties can be tailored to match or complement those of ceramic materials, including Gallium Arsenide, alumina, and silica. Thus, the cured articles can replace ceramic materials in many electronic and microwave applications, e.g., as specialized substrates for high speed digital and microwave circuits. Examples of microwave circuits including microstrip circuits, microstrip antennas, and stripline circuits. The cured products are also useful as rod antennas and chip carriers.

While well suited for its intended purposes, the circuit laminate materials described in U.S. Patent 5,223,568 do suffer from several drawbacks. For example, these prior art materials require a high temperature cure (e.g., lamination) of greater than about 250°C (482°F); and this requirement is problematic for several reasons. First, conventional circuit fabrication equipment often exhibit temperature limits of 180°C (360°F) which is below that of the 250°C (482°F) requirement. Still another drawback is that flammability ratings required by Underwriters Laboratory UL 94-VO lead to the need for inclusion of a flame retardant additive such as a bromine-containing fire retardant. Unfortunately, typical bromine-containing fire retardant additives cannot withstand the high temperature cure conditions of greater than 250°C; and will undergo decomposition and/or chemical degradation at these temperatures.

In addition to the foregoing need for lowering the cure (lamination) temperature of the circuit laminates, there is also a problem with the inherent tackiness associated with the polybutadiene or polyisoprene laminate preregs. Because of the tacky nature of the prepreg, it is not practically feasible to use a continuous, automated layup process for laminating circuit materials. Roll lamination equipment is commonly available and the ability to provide a polybutadiene or polyisoprene based prepreg of the type described in U.S. Patent 5,223,568 which also has the ability to be used in an automatic layup process will greatly reduce the manufacturing cost and processing time leading to a significant increase in the commercial success of the resultant circuit material products.

In addition to U.S. Patent 5,223,568, there are other prior art patents and literature of some interest which respect to the use of filled circuit laminates in general, and polybutadiene based circuit laminates in particular. For example, in an article entitled "A New Flame Retardant 1, 2-Polybutadiene Laminate" by N. Sawatari et al, IEEE Transactions on Electrical Insulation, Vo. EI-18, No. 2, April 1983, the limitations on presently used polybutadiene based laminates is discussed including the fact that 1,2-Polybutadiene (PBD) is difficult to control in the semicured condition (B-stage).

difficult to make non-tacky, highly flammable, and exhibits low copper bond. The article thereafter describes a composition which addresses these issues. The composition described uses a high percentage of very high molecular weight polybutadiene (PBD) to eliminate tackiness and B-staging. Also, a low molecular weight, modified PBD resin is used (as a minor component) to aid in copper bond and flow during lamination. There is no mention of using filler of any type.

U.S. Patent 5,264,065 to Kohm describes a base material for printed wiring boards where inert filler is used to control Z-axis CTE in fiberglass reinforced thermoset resins. U.S. Patent 5,264,065 discloses a range of 45-65 weight % fiberglass reinforcement and a range of 30 to 100 parts filler per 100 parts of the polymer. There is no disclosure in U.S. Patent 5,264,065 of a polybutadiene or like material for the resin system.

U.S. Patent 4,997,702 to Gazit et al discloses a circuit laminate having an epoxy resin system which also includes inorganic fillers or fibers in the range of 20-70 weight % of the total composite. The fibers include both glass and polymeric fibers and the fillers include clay or mineral (e.g., silica) particulate fillers.

U.S. Patent 4,241,132 to Pratt et al discloses a insulating board comprising a polymeric matrix such as polybutadiene and a filler consisting of polymeric filler (e.g., fibrous polypropylene). In all cases, the dielectric constant or dissipation factor of the resin matrix is matched to the fibrous reinforcement in order to obtain an isotropic composite.

European Patent No. 0 202 488 A2 discloses a polybutadiene based laminate wherein a high molecular weight, bromine-containing prepolymer is used to reduce tack and flammability of a 1, 2-polybutadiene resin. Similarly in Japanese Patent No. 04,258,658, a high molecular weight compound is added to a tacky PBD resin to control tack. The compound utilized is a halogen-containing bismaleimide which provides flammability resistance as well as good copper bonding and heat resistance. There is no mention of the use of fillers and the resulting laminate will have a relatively high dissipation factor.

An article entitled "1, 2-Polybutadienes-High Performance Resins for the Electrical Industry", R.E. Drake, ANTEC '84 pp. 730-733 (1984), generally discloses conventional polybutadiene resins for use in laminates and specifically discloses the use of reactive monomers to co-cure with the PBD.

U.K. Patent Application 2 172 892 A generally discloses laminates composed of styrene-containing and thermoplastic copolymers with unsaturated double bonds and polybutadiene.

Notwithstanding the foregoing examples of laminate composites, there continues to be a need for improved polybutadiene laminates.

Accordingly, it is an object to provide an electrical substrate material having a combination of electrical, chemical, mechanical and thermal properties which are not presently available.

This object is achieved by an electrical circuit material comprising:

(a) a thermosetting composition comprising a polybutadiene or polyisoprene resin and an unsaturated butadiene or isoprene containing polymer capable of participating in crosslinking with said polybutadiene or polyisoprene resin in an amount of from 25 to 50 volume percent;

(b) a woven fabric in an amount from 10 to 40 volume percent;

(c) a particulate filler in an amount of from 5 to 60 volume percent; and

(d) a free radical cure initiator.

The foregoing component ratios and particularly relatively high range of particulate filler is an important advantage in that this filled composite material leads to a prepreg which has very little tackiness and can therefore be easily handled by operators. This low tackiness feature allows for the use of conventional automated layup processing, including foil cladding, using one or more known roll laminators. While the composite material is tack-free enough to be handled relatively easily by hand, it is also tacky enough to be tacked to itself using a roll laminator (e.g., nip roller) at room temperature. In addition, another important advantage is the low amount of glass fabric filler relative to the higher range of particulate filler which leads to improved (lower) CTE in the Z axis or thickness direction, improved electrical performance (e.g., dissipation factor), lower cost and the ability to tailor dielectric constant through appropriate selection of particulate fillers.

Still another important advantage is that the cure temperature for lamination is significantly lower than required by U.S. Patent 5,223,568 with lamination temperatures typically in the range of 165°C to 218°C (330 to 425°F). The low temperature cure conditions allow for the use of bromine containing fire retardant additives as well as permitting the use of conventional circuit fabrication (e.g., lamination) equipment. The relatively low temperature cure is achieved using an appropriate amount of a free radical cure initiator preferably organic peroxides such as f. ex. dicumyl peroxide and t-butyl perbenzoate peroxide.

The electrical substrate material may include a plurality of woven webs (such as E-glass webs) embedded in a mixture of the polybutadiene or polyisoprene based resin system and inorganic filler (e.g., silica) laminated between one or two sheets of conductive foils (e.g., copper) to produce a circuit board material which is especially well suited for microwave applications. Of course, if very thin (e.g., less than 0.0762 mm (3 mil) thickness) cross-sections are desired, then only a single saturated web may be used for the dielectric.

A preferred composition has 18% woven glass, 41% particulate filler and 30% thermosetting matrix.

According to a preferred embodiment, the electrical circuit material comprises a thermosetting matrix in the amount of 25 to 50 vol. %, a glass woven fabric in the amount of 10 to 40 vol. % and at least one type of particulate filler in the amount of 5 to 60 vol. %. In addition, the electrical circuit material may include one or more organic peroxide initiators in an amount of 1,5 to 6 PHR and a bromine containing fire retardant additive in an amount effective to provide fire retardance.

The above-discussed and other features and advantages of the present invention will be appreciated and understood by those of ordinary skill in the art from the following detailed description and drawings.

The resin system, fillers, cross-linking agents, woven web, fire retardant additives, peroxide initiators, processing conditions and representative constructions together with Examples will now be discussed in detail.

Resin System

The resin system used in the present electrical substrate material is a thermosetting composition generally comprising (1) a polybutadiene or polyisoprene resin (or mixture thereof); and (2) an unsaturated butadiene or isoprene-containing polymer capable of participating in cross-linking with the polybutadiene or polyisoprene resin during cure. The polybutadiene or polyisoprene resins may be liquid or solid at room temperature. Liquid resins may have a molecular weight greater than 5,000 but preferably have a molecular weight of less than 5,000 (most preferably between 1,000 or 3,000). The preferably liquid (at room temperature) resin portion maintains the viscosity of the composition at a manageable level during processing. It also crosslinks during cure. Polybutadiene and polyisoprene resins having at least 90% 1,2 addition by weight are preferred because they exhibit the greatest crosslink density upon cure owing to the large number of pendent vinyl groups available for crosslinking. High crosslink densities are desirable because the electrical circuit substrates exhibit superior high temperature properties. A preferred resin is B3000 resin, a low molecular weight polybutadiene liquid resin having greater than 90 wt. % 1,2 addition. B3000 resin is commercially available from Nippon Soda, Ltd.

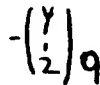
The unsaturated polymer preferably comprises a thermoplastic elastomer and more preferably includes a linear or graft-type block copolymer that preferably has a polybutadiene or polyisoprene block with at least 50% by weight, 1,2 addition and a thermoplastic block that preferably is styrene or a-methyl styrene. The high proportion of 1,2 addition in the polyisoprene or polybutadiene block leads to high crosslink densities after the curing step, as is the case with the polybutadiene or polyisoprene resin described above. A preferred copolymer is a styrene-butadiene-styrene triblock copolymer, e.g., Kraton DX1300 (commercially available from Shell Chemical Corp.).

The thermoplastic elastomer may also contain a second block copolymer similar to the first except that the polybutadiene or polyisoprene block is hydrogenated, thereby forming a polyethylene block (in the case of polybutadiene) or a ethylene-propylene copolymer (in the case of polyisoprene). When used in conjunction with the first copolymer, materials with greater "toughness" can be produced. Where it is desired to use this second block copolymer, a preferred material is Kraton GX1855 (commercially available from Shell Chemical Corp.) which is believed to be a mixture of styrene-high 1,2 butadiene-styrene block copolymer and styrene-(ethylene-propylene)-styrene block copolymer. Particularly preferred compositions are those in which the resin is polybutadiene, the first block copolymer is styrene-butadiene-styrene triblock copolymer ($m = n = 1$), and the second block is styrene-(ethylene-propylene)-styrene triblock copolymer ($m = n = 1$), the ethylene-propylene block being the hydrogenated form of an isoprene block.

Thus, in a preferred embodiment, the unsaturated polymer comprises a solid thermoplastic elastomer block copolymer having the formula $X_m(Y-X)_n$ (linear copolymer) or



(graft polymer) where Y is a polybutadiene or polyisoprene block, X is a thermoplastic block, and m and n represent the average block numbers in the copolymer, m being 0 or 1 and n being at least 1. The composition may further include a second thermoplastic elastomer block copolymer having the formula $W_p(Z-W)_q$ (linear copolymer) or



(graft copolymer) where Z is a polyethylene or ethylene-propylene copolymer block, W is a thermoplastic block, and p and q represent the average block numbers in the copolymer, p being 0 and 1 and q being at least 1.

Preferably, the polybutadiene or polyisoprene resin and the polybutadiene or polyisoprene block of the first block copolymer making up the thermoplastic elastomer have at least 90% by weight 1,2 addition. The volume to volume ratio of the polybutadiene or polyisoprene to the thermoplastic elastomer preferably is between 1:9 and 9:1, inclusive.

Other free radical curable polymers which can co-cure with butadiene polymers may be added (such that 1,2-butadiene polymers are still the major polymeric ingredient) for specific property or processing modifications. Such possible modification purposes include toughness, adherability to copper foil and copper plating, and pre-preg handling characteristics. These co-curable polymers include random and block copolymers of primarily 1,3-addition butadiene or isoprene with styrene, alpha-methyl styrene, acrylate or methacrylate, or acrylonitrile monomers; homopolymers or copolymers of ethylene, such as polyethylene, ethylene-propylene copolymer and ethylene-propylene-diene terpolymers, ethylene-ethylene oxide copolymers; natural rubber; norbornene polymers such as polydicyclopentadiene; hydrogenated diene polymers such as hydrogenated styrene-isoprene-styrene copolymers and butadiene-acrylonitrile copolymers; and others. Levels of these co-curable polymers should be less than 50% of the total polymeric component.

Particulate Filler Material

The volume % of the filler (based upon the combined volume of the resin system, woven fabric and particulate filler) is between 5 and 60%, inclusive and preferably between 30% and 50%. Examples of preferred fillers include titanium dioxide (rutile and anatase), barium titanate, strontium titanate, silica (particles and hollow spheres) including fused amorphous silica; corundum, wollastonite, polytetrafluoroethylene, aramide fibers (e.g., Kevlar), fiberglass, $\text{Ba}_2\text{Ti}_9\text{O}_{20}$, glass spheres, quartz, boron nitride, aluminum nitride, silicon carbide, beryllia, alumina or magnesia. They may be used alone or in combination.

In an important and preferred embodiment of this invention, the particulate filler is present in an amount which is (1) greater than the amount (in volume %) of thermosetting composition (preferably the ratio of filler to thermosetting composition is 45:55) and (2) greater than the amount (in volume %) of the woven fabric.

Particularly preferred fillers are rutile titanium dioxide and amorphous silica because these fillers have a high and low dielectric constant, respectively, thereby permitting a broad range of dielectric constants combined with a low dissipation factor to be achieved in the final cured product by adjusting the respective amounts of the two fillers in the composition. To improve adhesion between the fillers and resin, coupling agents, e.g., silanes, are preferably used.

As will be discussed hereinafter, the material described herein is preferably used as a dielectric substrate in a circuit laminate wherein a layer of metal is laminated thereto. Preferably, the filler material and quantity thereof is selected so as to provide the substrate with a coefficient of thermal expansion which is equal or substantially equal to the coefficient of thermal expansion of the metal layer.

Woven Web

The fiber reinforcement comprises woven, thermally stable webs of a suitable fiber, preferably glass (E, S, and D glass) or high temperature polyester fibers (e.g., KODEL from Eastman Kodak). The web is present in a amount of about 10 to 40 vol. %, and preferably about 15 to 25 vol. % with respect to the entire laminate. Such thermally stable fiber reinforcement provide the laminate with a means of controlling shrinkage upon cure within the plane of the laminate. In addition, the use of the woven web reinforcement renders a dielectric substrate with a relatively high mechanical strength.

Preferred examples of the woven fiberglass web used in the present invention are set forth in the following Table 1.

FIBERGLASS WOVEN WEBS

Table 1

Manufacturer	Style	Thickness (mm)	Thickness (in.)
Fiber Glast	519-A	0,0381	(0,0015)
Clark-Schwebel	112	0,0813	(0,0032)
Clark-Schwebel	1080	0,0635	(0,0025)
Burlington	106	0,0381	(0,0015)
Burlington	7628	0,1727	(0,0068)

Fire Retardant Additive

Preferably, the present electrical substrate material includes a flame retardant such as a bromine containing flame retardant in an amount of 20 to 60 vol. % or 2 to 6 PHR. Examples of suitable brominated flame retardants include Saytex BT 93W (Ethylene bistetrabromophthal imide), Saytex 120 (tetradecabromo diphenoxy benzene) or, Saytex 102 (Decabromo diphenoxyl oxide).

Curing Agent

A curing agent is added to the composition to accelerate the curing reaction. When the composition is heated, the curing agent decomposes to form free radicals, which then initiate crosslinking of the polymeric chains. Preferred curing agents are free radical cure initiators such as organic peroxides, e.g., dicumyl peroxide, t-butylperbenzoate and t-butylperoxy hexyne-3, all of which are commercially available. The peroxide curing agent is provided in a amount of between 1,5 and 6 (PHR).

Processing

In general, the thermosetting compositions are processed as follows. First, the (polybutadiene or polyisoprene resin, thermoplastic elastomer, particulate fillers, curing agents, flame retardants, and coupling agent (if any) are thoroughly mixed to form a slurry in conventional mixing equipment. The mixing temperature is regulated to avoid substantial decomposition of the curing agent (and thus premature cure). Mixing continues until the particulate filler is uniformly dispersed throughout the resin. The particulate filler may be pretreated with coupling agents (preferably silanes) in a separate step for more efficient use of the agents.

Next, conventional prepreg manufacturing methods can be employed. Typically the web is impregnated with the slurry, metered to the correct thickness, and then the solvent is removed (evaporated) to form a prepreg.

Referring now to the drawings, wherein like elements are numbered alike in the several FIGURES:

FIGURE 1 is a schematic representation of a processing line for the continuous manufacture of the prepreg in accordance with the present invention;

FIGURE 2 is a cross-sectional elevation view of a circuit substrate material in accordance with the present invention; and

FIGURES 3-5 are test data depicting the improved (lower) tackiness of the B-staged circuit substrate in accordance with the present invention.

One processing system useful in making a prepreg is shown in FIGURE 1 and includes (from left to right) a roll 10 of woven glass web 11 which unwinds through a first accumulator 12 to a series of drive rolls 14. The web 11 then passes into the coating area 16 where the web is passed through a saturation tank 20 (which contains the mixture of polymer, particulate filler, solvent and other components) and then through a pair of metering rolls 22. The web 11 thereafter travels the length of a drying tower 18 for a selected period of time until the solvent is evaporated from the web whereupon the web passes through drive rolls 28, a second accumulator 30 and finally web 11 (which is now a prepreg) is wound onto roll 32.

The lamination process entails a stack-up of one or more prepreg layers between one or two sheets of conductive foil (copper). This stack-up is then densified and cured via lamination or a combination of lamination and oven baking.

The stack-up is cured in a conventional peroxide cure step; typical cure temperatures are between 165 and 218°C (330 and 425°F). Unlike U.S. Patent 5,223,568, no additional high temperature cure step is needed to increase crosslink density. It will be appreciated that the U.S. Patent 5,223,568 requires a high temperature cure where the temperature is greater than about 250°C but less than the decomposition temperature of the resin (typically about 400°C).

Referring now to FIGURE 2, a cross-sectional view of electrical substrate material in accordance with the present invention is shown generally at 40. Electrical substrate 40 has been laminated in accordance with one of the processes described above wherein a woven web 42 is impregnated with a resin system/filler composition 44 and laminated between two copper foils 46, 46' to produce a circuit board laminate. As discussed above with reference to the processing conditions, the resin system 44 may either be cast onto woven web 42 using known prepreg manufacturing equipment or web 42 may be saturated by resin system 44 by sandwiching web 42 between a pair of bond plys formed from resin system 44 and laminating the stack up together with the copper cladding 46, 46'. While FIGURE 2 depicts a single layer of woven web 42, it will be appreciated that typically a plurality of layers of saturated web 12 will be used in forming circuit laminates. However, a single layer as shown in FIGURE 2 is desirable where very thin cross-sections (less than 0,0762 mm (3 mils)) are required.

Examples

The following non-limiting examples further describe the present electrical substrate material.

A. Tackiness

In an effort to quantify the tackiness of the prepreg of this invention, a peel test was developed and applied to a number of samples.

Test Description

Attempting to simulate a 90° peel test, an Instron (Model 1125) was used to peel apart 2 layers of prepreg. The individual layers of prepreg were 2,54 cm (1") wide and 30,5 cm (12") long and were stuck together by rolling a 4,54 kg (10 lb) roller over them in the lengthwise direction. A 22,7 kg (50 lb) tensile load cell was used in conjunction with a 15 ipm crosshead speed to measure the peel force or tack. For verification of the data, the tests were duplicated using a 4,54 kg (10 lb) cell and 12 ipm.

Test Samples

Four prepreg formulations were created for this test. Using only 106 style fiberglass, prepregs were made in which the particulate filler, resin and rubber contents varied.

Prepreg Component Quantities - (all % BVOL)					
Sample	Filler	Resin (PBD)	Rubber (SBS)	Woven Glass	Other
2075-62-1	25	32	20	18	5
2075-62-2	34	26	16	18	6
2075-62-3	25	41	11	18	5
2075-62-5	34	34	9	18	5

Results

The measured peel values range from 0 to 0,35 pli. FIGURE 3 plots the tack versus SBS (rubber) content for the two filler loadings used. From this plot, the resulting tack is more sensitive to rubber content at the lower filler loading. Alternatively, FIGURE 4 plots the tack versus filler content. In this case, the resulting tack is more sensitive to filler content at the lower rubber loading. FIGURES 3 and 4 lead to the conclusion that the combination of filler and rubber volumes effect tack. If one looks at the resulting resin contents versus tack (FIGURE 5), there is a good correlation between resin

volume present and tack. Put simply, it appears that an important factor for tackiness is the amount of resin present and to reduce tack it does not matter whether the resin is displaced by filler or rubber so long as the resin is displaced.

B. Example Formulations:

The following five examples show representative electrical, thermal and mechanical data on some of the laminates of the present invention. Preferably, the dissipation factor of the resultant laminate is less than or equal to 0,007 which renders this material well suited for use in microwave applications.

Example 1: This is a preferred embodiment. The laminate consisted of five layers of prepreg for a total dielectric thickness of 0,584 mm (0,023"). Formulation details are contained in Table 1. Note the high filler and low rubber contents. Table 2 briefly reports a few of the resulting properties.

Example 2: This sample contained a particulate filler loading lower than the preferred embodiment but had a higher rubber content. The laminate was made with five layers of 1080 woven glass resulting in a dielectric thickness of 0,53 mm (0,021").

Example 3: This sample contained titania (TiO₂) particulate filler compared to the silica (SiO₂) found in the other examples. The laminate contained 10 layers of 1080 woven glass resulting in a dielectric thickness of 0,711 mm (0,028").

Example 4: This laminate had the rubber replaced in the formulation with more resin. The laminate's construction utilized four layers of 1080 woven glass and resulted in a dielectric thickness of 0,406 mm (0,016").

Example 5: This sample contained more rubber than resin. The resulting laminate was 0,508 mm (0,020") thick and utilized five layers of 1080 woven glass.

Examples 1-5 Constructions (units = %BWT)					
Example	1	2	3	4	5
B3000 Resin	14,6	13,5	12	21,2	4,4
D1300 Rubber	3,8	9,3	3	0	13,1
FB-35 Silica	0	44,7	0	0	51,3
Minsil 5 Silica	51	0	0	45,7	0
Ticon HG Titania	0	0	53,2	0	0
Woven Glass	25	26	27	26	25
Silane	0,5	0,4	0,6	0,4	0,5
Brominated Flame Retardant	4,5	4,6	3,7	5,3	4,4
Catalyst (peroxide)	0,6	1,5	0,5	1,4	1,3

B3000 resin by Nippon Soda, D1300 rubber (Kraton) by Shell, FB-35 silica is fused silica from Denka, Minsil 5 silica is a fused silica from Minco, Ticon HG titania by TAM woven glass by Clark-Schwebel.

Examples 1-5 Properties					
Example	1	2	3	4	5
Dielectric Constant	3,47	3,35	9,54	3,22	3,42
Dissipation Factor	0,0035	0,0042	0,0059	0,0053	0,0035
Specific Gravity (g/cc)	1,83	1,75	2,47	1,76	1,83
Copper Bond (pli)	4,4	5	2,1	3,2	3,7
Water Absorption (%)	N/A	0,09	N/A	N/A	0,67

The DK values reported above are actually the averages of the measured DK's from a 1-10 GHz frequency sweep. The Df values reported above are the lowest recorded value of a given 1-10 GHz frequency sweep.

Specific gravity test method: ASTM D792-91
 5 Copper bond: IPC-TM-650 2.4.8
 Water absorption: IPC-TM-650 2.6.2.1 (w/48hr exp.)

In general, the preferred formulations of the present invention minimize fiber content and maximize particulate filler content. This high particulate filler content (preferred ratio of resin to filler is 45:55) leads to improved (lower) CTE in the Z-axis direction, improved electrical performance, lower cost and other features and advantages. While the prior art discussed above generally discloses filled polybutadiene laminates and laminates based on other resin systems which employ fiber and particulate fillers, no prior art to which Applicants are aware utilize the combination of:

1. thermosetting matrix comprised of polybutadiene or polyisoprene resin and an unsaturated butadiene or isoprene containing polymer in an amount of 25 to 50 volume %;
2. woven fabric reinforcement in an amount from 10 to 40 vol. %; and
3. particulate filler in an amount of 5 to 60 volume %.

Prferably, the present invention utilizes a higher particulate filler level and a lower woven fabric level. Advantagously, the use in the thermosetting composition of a high molecular weight copolymer permits the use of these higher levels of particulate fillers, all of which leads to improved rheological control, reduced tack and reduced shrinkage. More particularly, the combination of an extremely high loading level of particulate filler, woven glass and an unsaturated polymer while still being processable using standard industry equipment represents an important advance in the circuit materials field. In addition, the unexpected result that the particulate filler can be used to eliminate tackiness of the liquid polybutadiene resin represents still another important advantage of this invention

Claims

1. An electrical circuit material comprising:

(a) a thermosetting composition comprising a polybutadiene or polyisoprene resin and an unsaturated butadiene or isoprene containing polymer capable of participating in crosslinking with said polybutadiene or polyisoprene resin in an amount of from 25 to 50 volume percent;

(b) a woven fabric in an amount from 10 to 40 volume percent;

(c) a particulate filler in an amount of from 5 to 60 volume percent; and

(d) a free radical cure initiator.

2. The material of claim 1 characterized in that the woven fabric is glass fabric.

3. The material of claim 1 or 2 characterized in that said particulate filler is present in an amount by volume which is greater than the amount of woven fabric.

4. The material of any of the claims 1 to 3 characterized in that:

said particulate filler is present in an amount by volume which is greater than the amount of thermosetting composition.

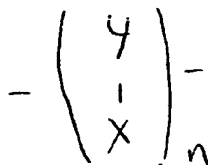
5. The material of any of the claims 1 to 4 characterized in that said polybutadiene or polyisoprene resin is liquid at room temperature.

6. The material of any of the claims 1 to 5 characterized in that said polybutadiene or polyisoprene resin has a molecular weight less than 5,000.

7. The material of any of the claims 1 to 4 characterized in that said polybutadiene or polyisoprene resin is solid at room temperature.

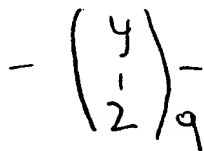
8. The material of any of the claims 1 to 7 characterized in that said unsaturated butadiene or isoprene containing polymer comprises a solid polymer.

9. The material of any of the claims 1 to 7 characterized in that said unsaturated butadiene or isoprene containing polymer comprises a liquid polymer.
10. The material of any of the claims 1 to 9 characterized in that said polybutadiene or polyisoprene resin includes pendent vinyl groups available for crosslinking.
11. The material of any of the claims 1 to 10 characterized in that said unsaturated butadiene or isoprene containing polymer has pendent vinyl groups available for crosslinking.
12. The material of any of the claims 1 to 11 characterized in that said unsaturated polymer is a copolymer of isoprene or butadiene and a second monomer.
13. The material of claim 12 characterized in that said second monomer is styrene or a-methyl styrene.
14. The material of claim 12 characterized in that said copolymer is a thermoplastic elastomer block copolymer having the formula $X_m-(Y-X)_n$ or the formula



where in each formula Y is a block comprising isoprene or butadiene units, X is a thermoplastic block, and m and n represent the average block numbers in said copolymer, m being 0 or 1 and n being at least 1.

15. The material of any of the claims 1 to 14 characterized in that said unsaturated butadiene or isoprene containing polymer comprises a thermoplastic elastomer block copolymer having the formula $W_p-(Z-W)_q$ or the formula



where in each formula Z is a polyethylene or ethylene-propylene copolymer block, W is a thermoplastic block, and p and q represent the average block numbers in said copolymer, p being 0 or 1 and q being at least 1.

16. The material of any of the claims 1 to 15 characterized in that said unsaturated polymer is a styrene-butadiene-styrene triblock copolymer.
17. The material of any of the claims 1 to 15 characterized in that said unsaturated polymer is a styrene-butadiene-styrene triblock copolymer, and said block copolymer is a styrene-ethylene-propylene-styrene triblock copolymer.
18. The material of any of the claims 1 to 17 characterized in that:
said particulate filler is a quantity of dielectric filler chosen to provide to said electrical substrate material a preselected dielectric constant, said added filler being dispersed substantially uniformly throughout said composition.
19. The material of any of the claims 1 to 18 characterized in that:
said dielectric filler is selected from the group consisting of titanium dioxide, barium titanate, strontium titanate, silica, fused amorphous silica, corundum, wollastonite, polytetrafluoroethylene, aramide fibers, fiberglass, $Ba_2Ti_9O_{20}$, glass spheres, quartz, boron nitride, aluminum nitride, silicon carbide, beryllia, alumina or magnesia.

20. The material of any of the claims 1 to 19 characterized in that said particulate filler is present in an amount of between 30 and 50% volume percent.

21. The material of any of the claims 1 to 20 characterized in that said woven fabric is present in an amount of between 15 and 25 volume percent.

22. The material of any of the claims 1 to 21 further including:
a metal layer having a preselected coefficient of thermal expansion and;
said filler and the quantity thereof providing to said electrical substrate material a coefficient of thermal expansion substantially equal to that of said metal layer.

23. The material of any of the claims 1 to 22 further including a crosslinking agent to said thermosetting composition.

24. The material of claim 23 characterized in that:
said crosslinking agent is selected from the group consisting essentially of triallyl cyanurate, diallyl phthalate, divinylbenzene, a multifunctional acrylate monomer, or a combination thereof.

25. The material of any of the claims 1 to 24 characterized in that said electrical circuit substrate comprises a microwave circuit substrate.

26. The material of any of the claims 1 to 25 including: a flame retardant.

27. The material of claim 26 characterized in that said flame retardant comprises a bromine containing flame retardant.

28. The material of any of the claims 1 to 27 characterized in that said electrical circuit material has a dissipation factor of equal to or less than 0,007.

29. The material of any of the claims 1 to 28 characterized in that said unsaturated butadiene or isoprene containing polymer is selected from the group consisting of:

(1) random and block copolymers of primarily 1,3-addition butadiene or isoprene with styrene, alpha-methyl styrene, acrylate or methacrylate, or acrylonitrile monomers, (2) homopolymers or copolymers of ethylene, (3) natural rubber, (4) norbornene polymers, (5) hydrogenated diene polymers and (6) butadiene-acrylonitrile copolymers.

30. The material of any of the claims 1 to 28 characterized in that said unsaturated butadiene or isoprene containing polymer comprises homopolymers or copolymers of ethylene selected from the group consisting of:
polyethylene, ethylene-propylene copolymer and ethylene-propylene-diene terpolymers and ethylene-ethylene oxide copolymers.

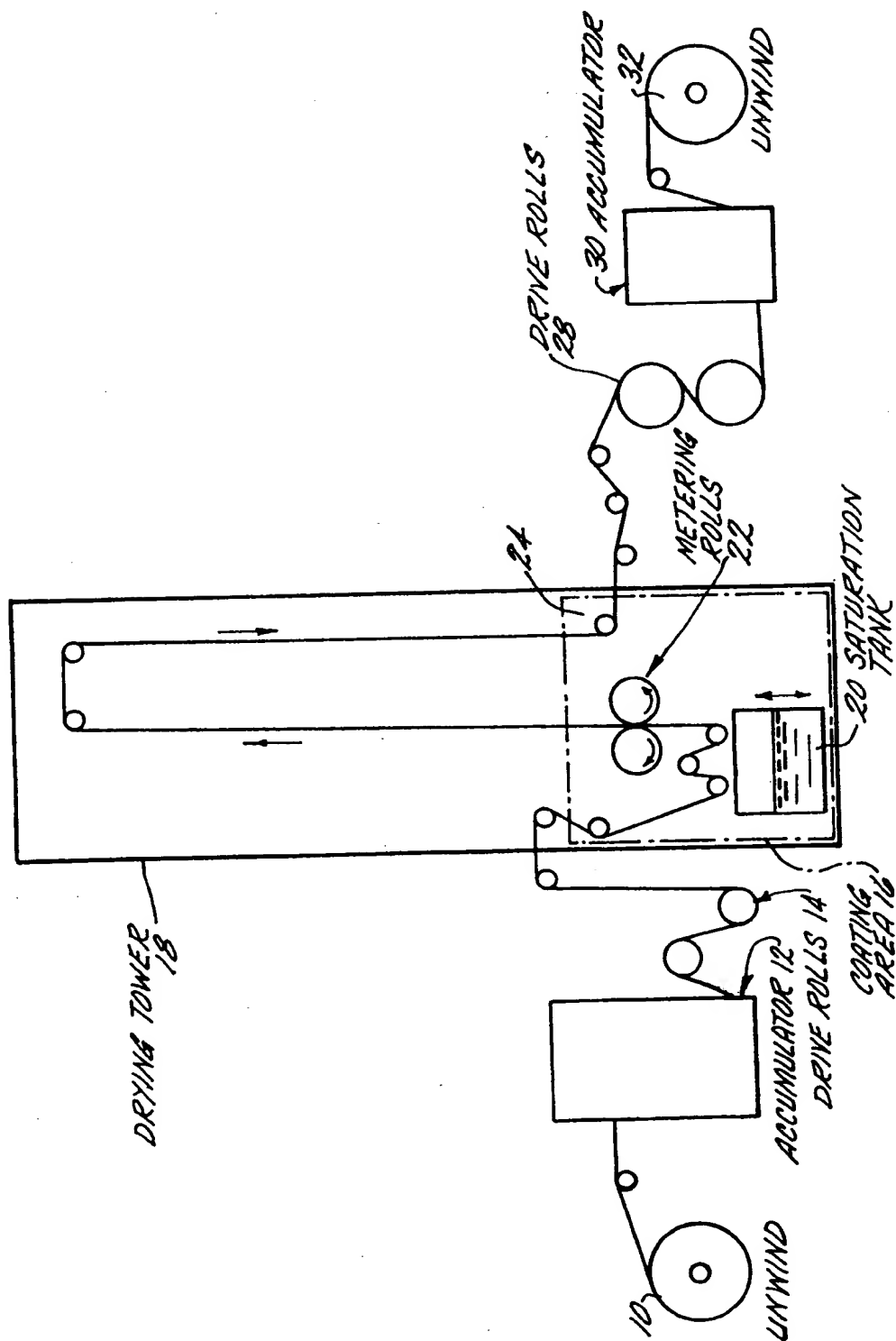


FIG. 1

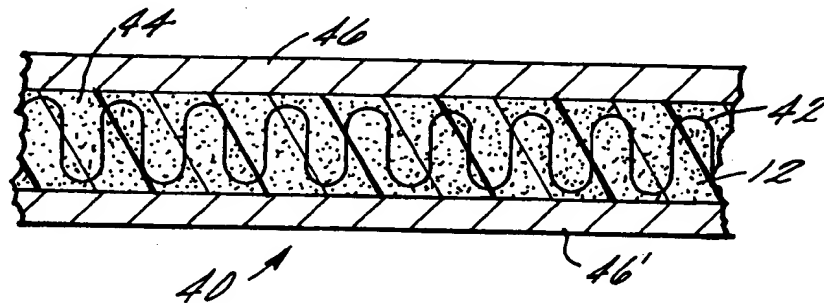


FIG. 2

PREPREG TACKINESS TEST RESULTS

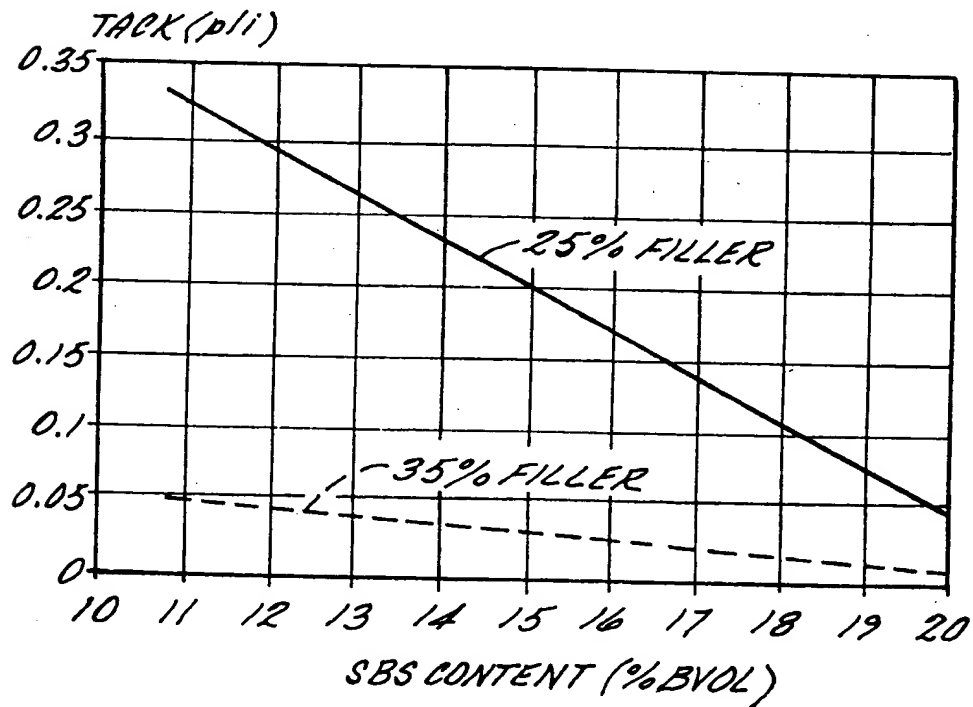
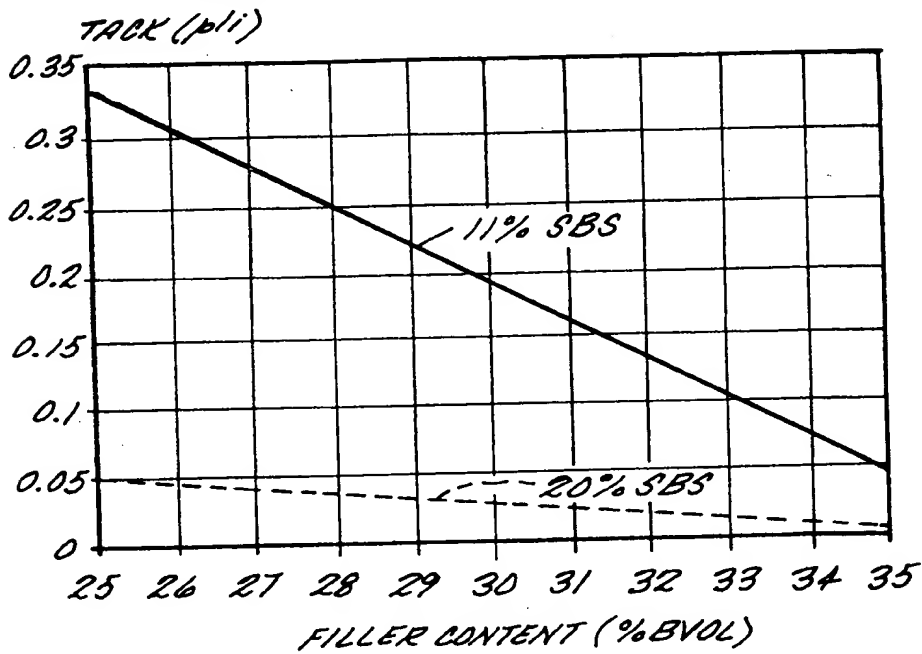
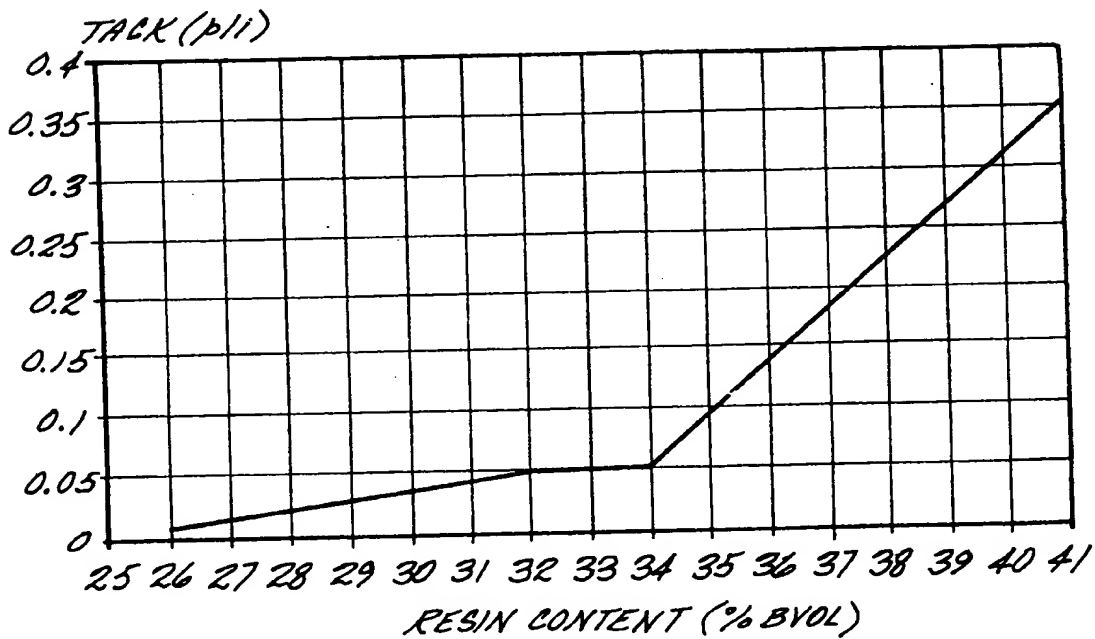


FIG. 3

PREPREG TACKINESS TEST RESULTS

FIG. 4

PREPREG TACKINESS TEST RESULTS

FIG. 5



European Patent
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EUROPEAN SEARCH REPORT

Application Number
EP 95 11 4852

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.6)
D,A	US-A-5 223 568 (V.R.LANDI ET AL.) * column 2, line 47 - line 54; claims 1,11,16 *		C08L9/00 H05K1/03
A	GB-A-1 195 567 (TRW INC) * claims 4,7 *		
			TECHNICAL FIELDS SEARCHED (Int.Cl.6)
			C08L H05K
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 23 January 1996	Examiner Van Humbeeck, F
<p>CATEGORY OF CITED DOCUMENTS</p> <p>X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document</p> <p>T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document</p>			

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